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PATENT ABSTRACTS OF JAPAN

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H01L 23/48(21) Application number: **55141491**(71) Applicant: **MITSUBISHI ELECTRIC CORP**(22) Date of filing: **09.10.80**(72) Inventor: **MIWA JUNKO****(54) LEAD FRAME FOR SEMICONDUCTOR DEVICE****(57) Abstract:**

PURPOSE: To prevent the destruction of a semiconductor element due to a thermal stress generated when the element and a die pad for mounting the same are bonded together, by forming slits in the die pad.

CONSTITUTION: A die pad 2a is supported by an X-shaped suspended pin 3a whose one end is connected to a frame 9, and has slits in the direction of the suspended pin 3a and the direction perpendicular thereto in order to make the bending rigidity small. Accordingly, it is possible to lessen the bending deformation and stress generated owing to the difference in the coefficient of linear expansion between the die pad 2a and a silicon element 5, so that the destruction of the element 5 can be prevented when it is bonded.

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